



GUH Circuit Industry (PG) Sdn Bhd

HDI CAPABILITIES

Capabilities (能力)	MP Capabilities (量产能力)	Sample Capabilities (样品能力)
Layer Count (最大层数)	4 ~ 10 Layers	4 ~ 16 Layers
PCB Thickness (板厚范围)	0.4mm ~ 3.2mm	0.3mm ~ 3.2mm
Minimum Annular Ring (最小焊环)	Via : 100μm Laser Via : 75μm	Via : 100μm Laser Via : 50μm
Pre Preg - Standard Glass Cloth (标准玻纤布)	1027 / 1037 / 106 / 1080	1027 / 1037 / 106 / 1080
Build Up Technology (HDI 叠加阶层)	1+N+1	2+N+2
Minimum Laser Drill Size (最小镭射孔径)	75μm	75μm
Via Type (镀孔类型)	Blind via , Buried via	Blind via , Buried via
Minimum Mechanical Drilled Size (最小钻径)	0.15mm (150μm)	0.15mm (150μm)
Minimum Target Pad (最小Target Pad)	D + 150μm (D Laser Via)	D + 100μm (D Laser Via)
Blind Via Aspect Ratio (盲孔纵横比)	≤ 0.9	≤ 1.0
Copper Thickness (铜厚范围)	1oz, 2oz, 3oz, 5oz	1oz, 2oz, 3oz, 5oz
Maximum Dimple (最大Dimple)	20μm	10μm
Minimum Line Width / Spacing (最小线宽/线距)	75μm / 75μm	75μm / 75μm
Solder Mask Registration (焊阻对位精度)	± 50μm	± 37.5μm
Minimum Solder Mask Bridge (最小阻焊桥)	Green/Red ± 75μm Blue/Black ± 100μm	Green/Red ± 75μm Blue/Black ± 100μm
Maximum PCB Size (最大生产板尺寸)	520mm X 620mm	520mm X 620mm
Minimum PCB Size (最小生产板尺寸)	16mm X 16mm	16mm X 16mm
Surface Finishing (表面处理)	OSP, ENIG, Hard Gold, HASL, Carbon, Peelable Mask, Selective Surface	OSP, ENIG, Hard Gold, HASL, Carbon, Peelable Mask, Selective Surface
Impedance Control Tolerance (阻抗公差)	± 10%	± 10%
Special Capability (特殊工艺)	-	Non-wire Gold Finger, Hybrid Material, Sequential Lamination

~ The above production capabilities serve as a general guideline and is subject to change ~